

# BRSC65R380ZFA

Rev.B Jun.-2026

## 描述 / Descriptions

TO-220F 塑封封装 SiC N 沟道 MOS 场效应管。

SiC N-CHANNEL MOSFET in a TO-220F Plastic Package.

## 特征 / Features

$V_{DS}=650V$  ;  $I_D=10A$

$R_{DS(on)}@15V \leq 390m\Omega$  (Type.300m $\Omega$ )

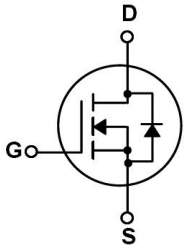
$R_{DS(on)}@18V \leq 380m\Omega$  (Type.222m $\Omega$ )

## 用途 / Applications

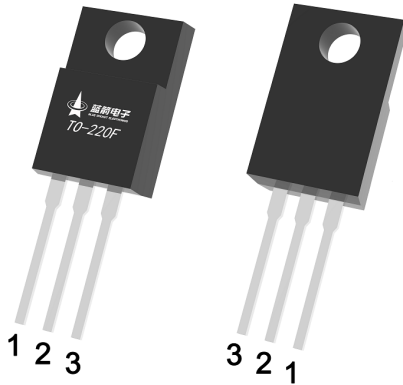
LED 驱动电源、PD 快充充电器、PC 电源适配器、空调、电动自行车充电器。

LED driver, PD charger, PC adapter, Air-conditioning, E-bike charger.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN 1 : G

PIN 2 : D

PIN 3 : S

## 印章代码 / Marking

见印章说明。

See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Tc=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V <sub>DSS</sub>	650	V
Continuous DC Drain Current for R <sub>th(j-c,typ.)</sub> , Limited by T <sub>VJ(max)</sub>	I <sub>D</sub> (Tc=25°C)	10	A
	I <sub>D</sub> (Tc=100°C)	8.5	A
Peak Drain Current, tp Limited by T <sub>VJ(max)</sub>	I <sub>DM</sub>	18	A
Gate-Source Max Voltage	V <sub>GS,max</sub>	-10/+22	V
Gate-Source Operate Voltage	V <sub>GS,op</sub>	0/+15	V
Single Pulse Avalanche Energy	E <sub>AS</sub>	17	mJ
Power Dissipation or R <sub>th(j-c,typ.)</sub>	P <sub>D</sub> (Tc=25°C)	25	W
Operating and Storage Temperature Range	T <sub>VJ</sub> , T <sub>STG</sub>	-55 to 175	°C
MOSFET/Body Diode Junction-Case Thermal Resistance	R <sub>th(j-c)</sub>	6	°C/W

**电性能参数 / Electrical Characteristics(Tc=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =100μA	650			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =3.5mA	2		4	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =650V V <sub>GS</sub> =0V		0.1	20	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =22V V <sub>DS</sub> =0V			250	nA
Source-Gate Leakage Current	I <sub>SGS</sub>	V <sub>GS</sub> =-10V V <sub>DS</sub> =0V			250	nA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =15V I <sub>D</sub> =5A		300	390	mΩ
		V <sub>GS</sub> =15V I <sub>D</sub> =5A T <sub>VJ</sub> =175°C		321		
		V <sub>GS</sub> =18V I <sub>D</sub> =5A		222	380	
		V <sub>GS</sub> =18V I <sub>D</sub> =5A T <sub>VJ</sub> =175°C		266		
Body Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V I <sub>S</sub> =2.5A		3.6		V
Continuous DC Source Current	I <sub>S</sub>			9.7		A
Peak Reverse Drain Current,	I <sub>SM</sub>			17		A
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> = 0V, I <sub>SD</sub> =5A, V <sub>R</sub> =400V, di/dt=1.1kA/us		10.9		ns
Reverse Recovery Charge	Q <sub>rr</sub>			28		nC
Peak Reverse Recovery Current	I <sub>rrm</sub>			3.9		A
Reverse Recovery Energy	E <sub>rr</sub>			0.22		μJ

## 电性能参数 / Electrical Characteristics(Tc=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=0/15V$ $L=600\mu H$ $V_{DD}=400V$ $I_D=5A$ $R_g=4.3\Omega$		16.5		ns
Turn-On Rise Time	$t_r$			11.3		
Turn-Off Delay Time	$t_{d(off)}$			21.2		
Turn-Off Fall Time	$t_f$			12.7		
Turn-On Switching Loss	$E_{on}$			47.6		μJ
Turn-Off Switching Loss	$E_{off}$			4.0		
Total Switching Energy	$E_{tot}$			51.6		
Gate resistance	$R_g$	$V_{AC}=25mV$ $f=1MHz$		26		Ω
Input Capacitance	$C_{iss}$	$V_{DS}=400V$ $V_{GS}=0V$ $f=1MHz$		228		pF
Output Capacitance	$C_{oss}$			17		
Reverse Transfer Capacitance	$C_{rss}$			1.4		
Total Gate Charge	$Q_g$	$V_{GS}=0/15V,$ $V_{DS}=400V,$ $I_D=5A$		8.8		nC
Gate Source Charge	$Q_{gs}$			3.3		
Gate Drain Charge	$Q_{gd}$			1.2		

## 电参数曲线图 / Electrical Characteristic Curve

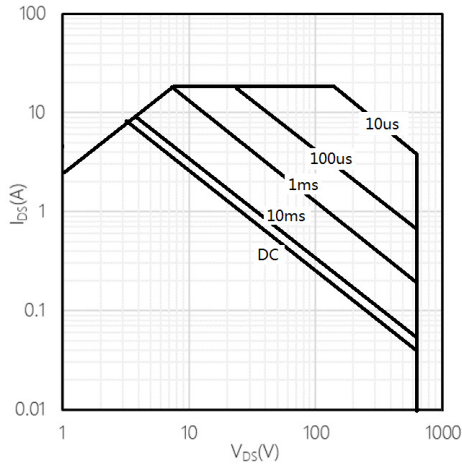


Fig1. Safe operating area (SOA)

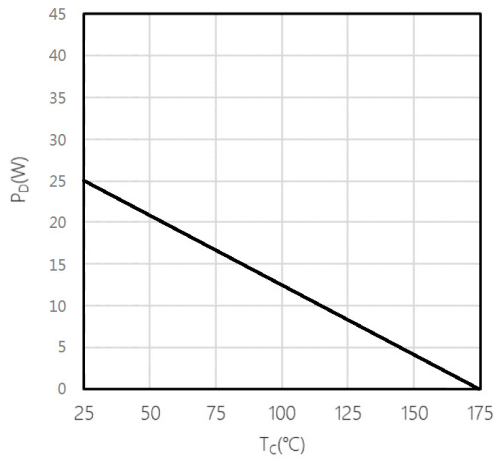


Fig2. Power dissipation

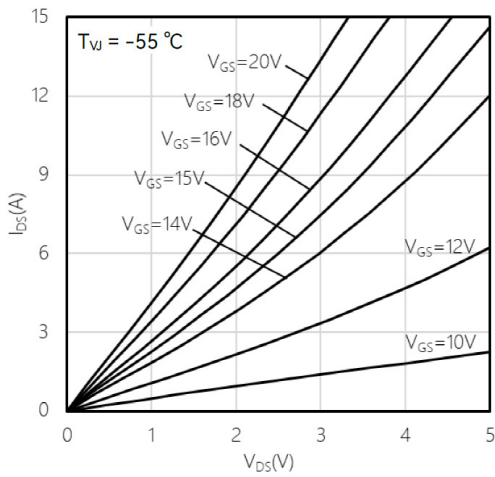


Fig3. Typical output characteristic

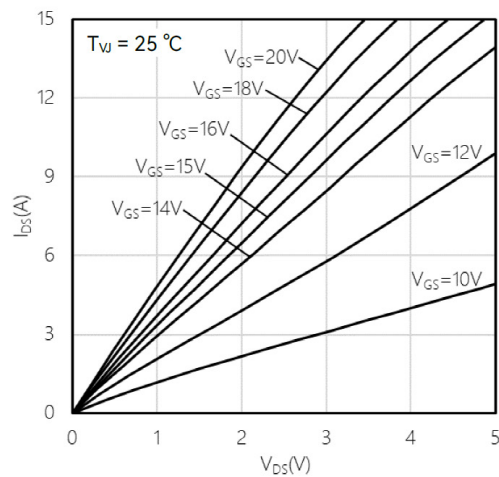


Fig4. Typical output characteristic

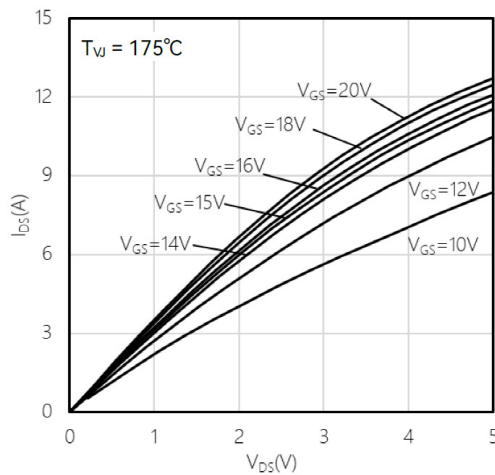


Fig5. Typical output characteristic

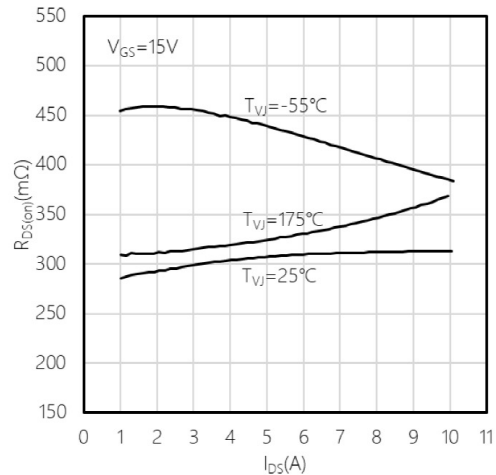


Fig6. Typical on-state resistance as a function of drain current

电参数曲线图 / Electrical Characteristic Curve

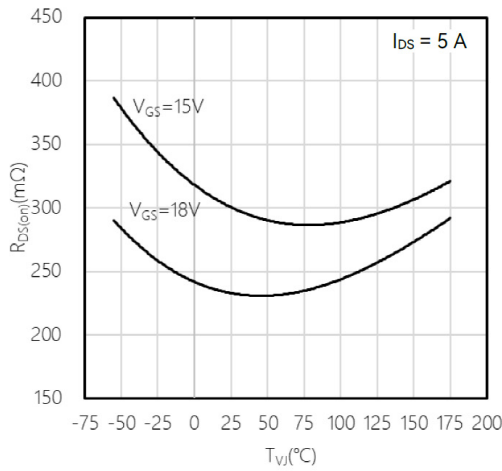


Fig7. Typical on-state resistance as a function of temperature

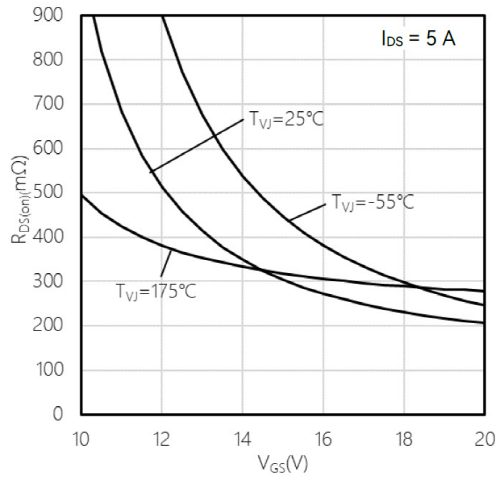


Fig8. Typical on-state resistance as a function of V\_GS

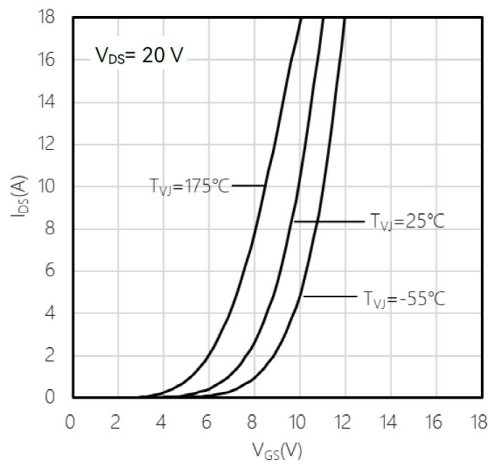


Fig9. Typical transfer characteristic

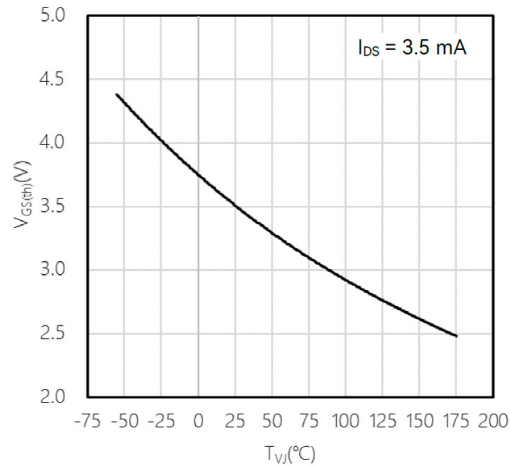


Fig10. Typical gate-source threshold voltage as a function of junction temperature

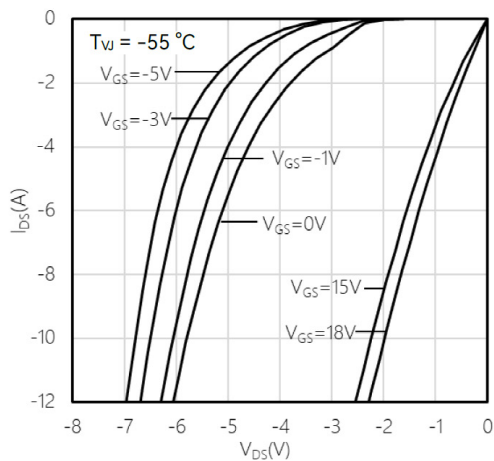


Fig11. Typical reverse drain current as function of reverse drain voltage

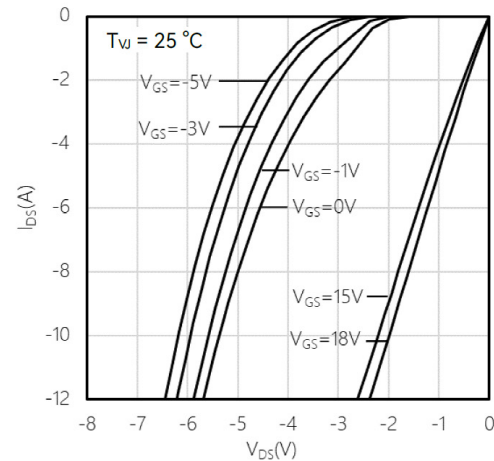


Fig12. Typical reverse drain current as function of reverse drain voltage

电参数曲线图 / Electrical Characteristic Curve

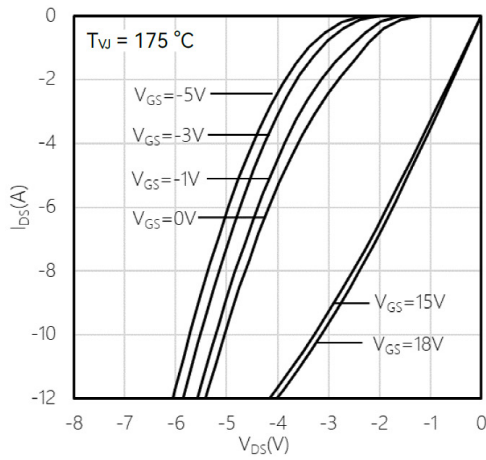


Fig13. Typical reverse drain current as function of reverse drain voltage

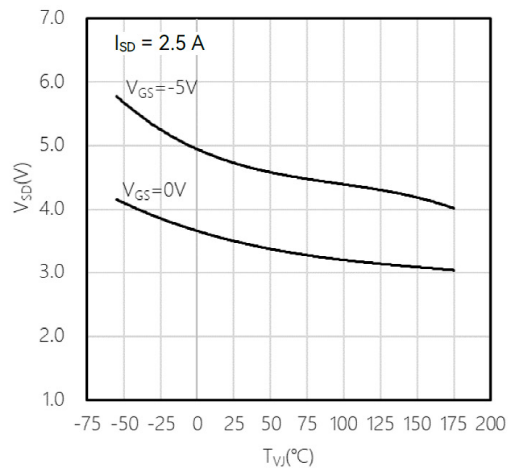


Fig14. Typical reverse drain voltage as function of junction temperature

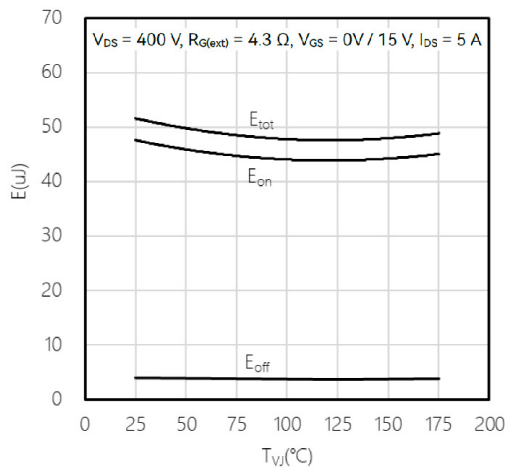


Fig15. Typical switching energy as a function of junction temperature, 2nd device own body diode: VGS = 0V

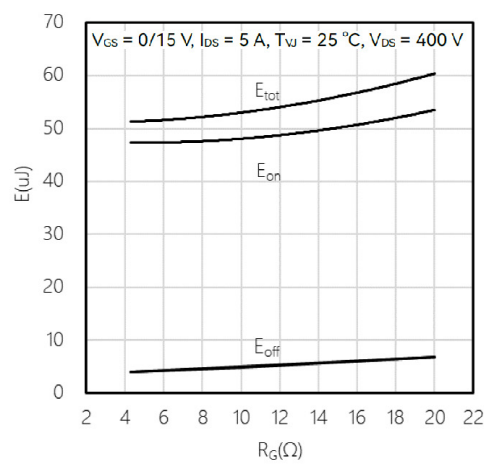


Fig16. Typical switching energy losses as a function of gate resistance, 2nd device own body diode: VGS = 0V

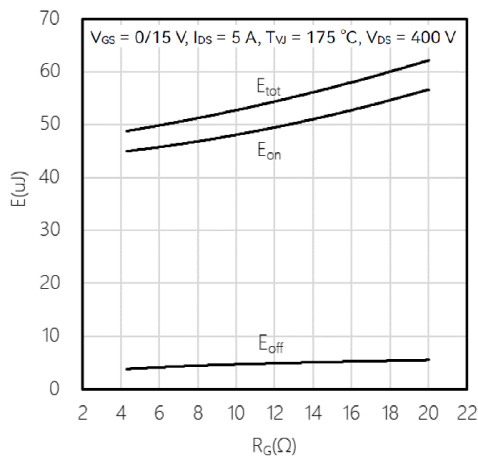


Fig17. Typical switching energy losses as a function of gate resistance, 2nd device own body diode: VGS = 0V

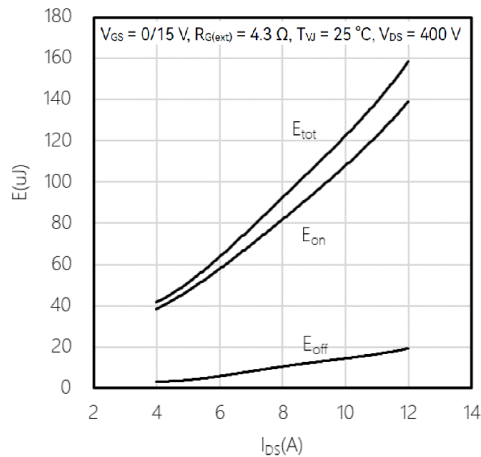


Fig18. Typical switching energy losses as a function of Ids, 2nd device own body diode: VGS = 0V

电参数曲线图 / Electrical Characteristic Curve

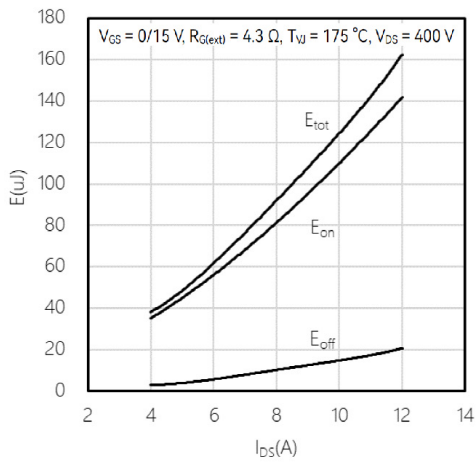


Fig19. Typical switching energy losses as a function of IDS, 2nd device own body diode: VGS = 0V

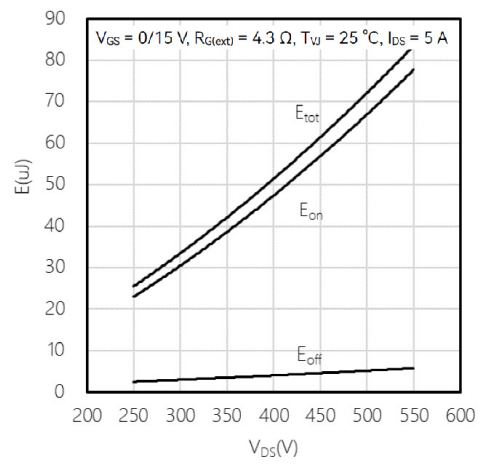


Fig20. Typical switching energy losses as a function of VDS, 2nd device own body diode: VGS = 0V

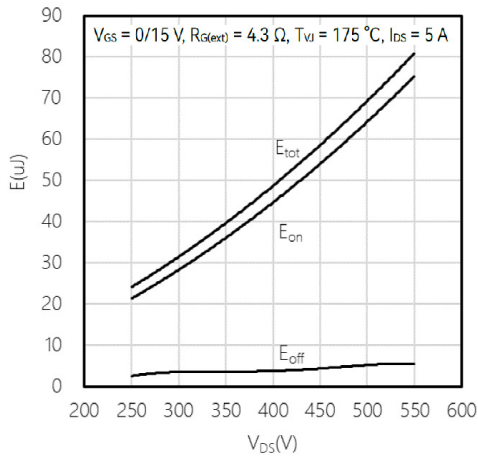


Fig21. Typical switching energy losses as a function of VDS, 2nd device own body diode: VGS = 0V

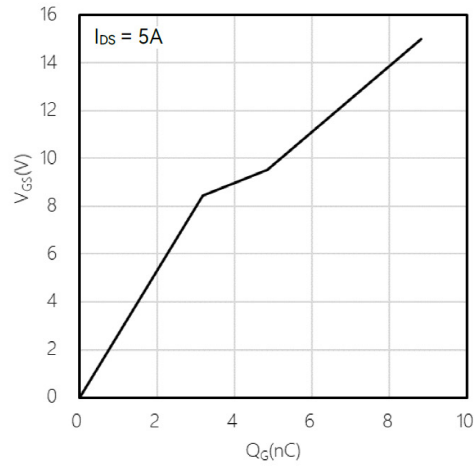


Fig22. Typical gate charge

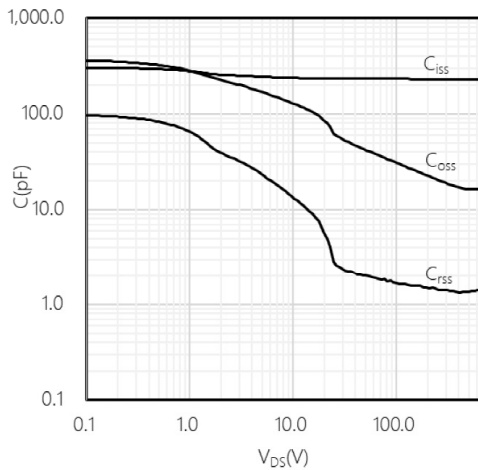


Fig23. Typical capacitance as a function of drain-source voltage

电参数曲线图 / Electrical Characteristic Curve

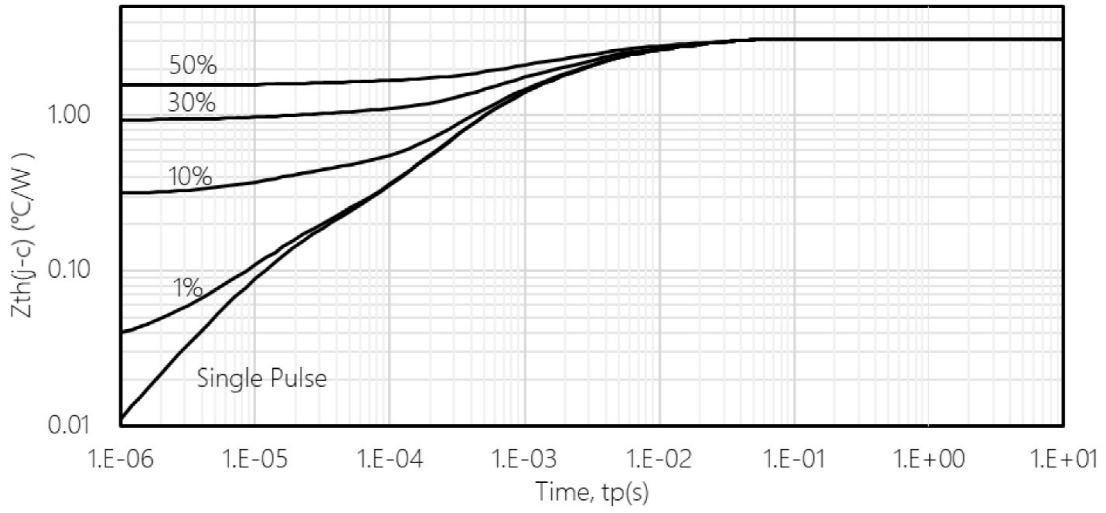
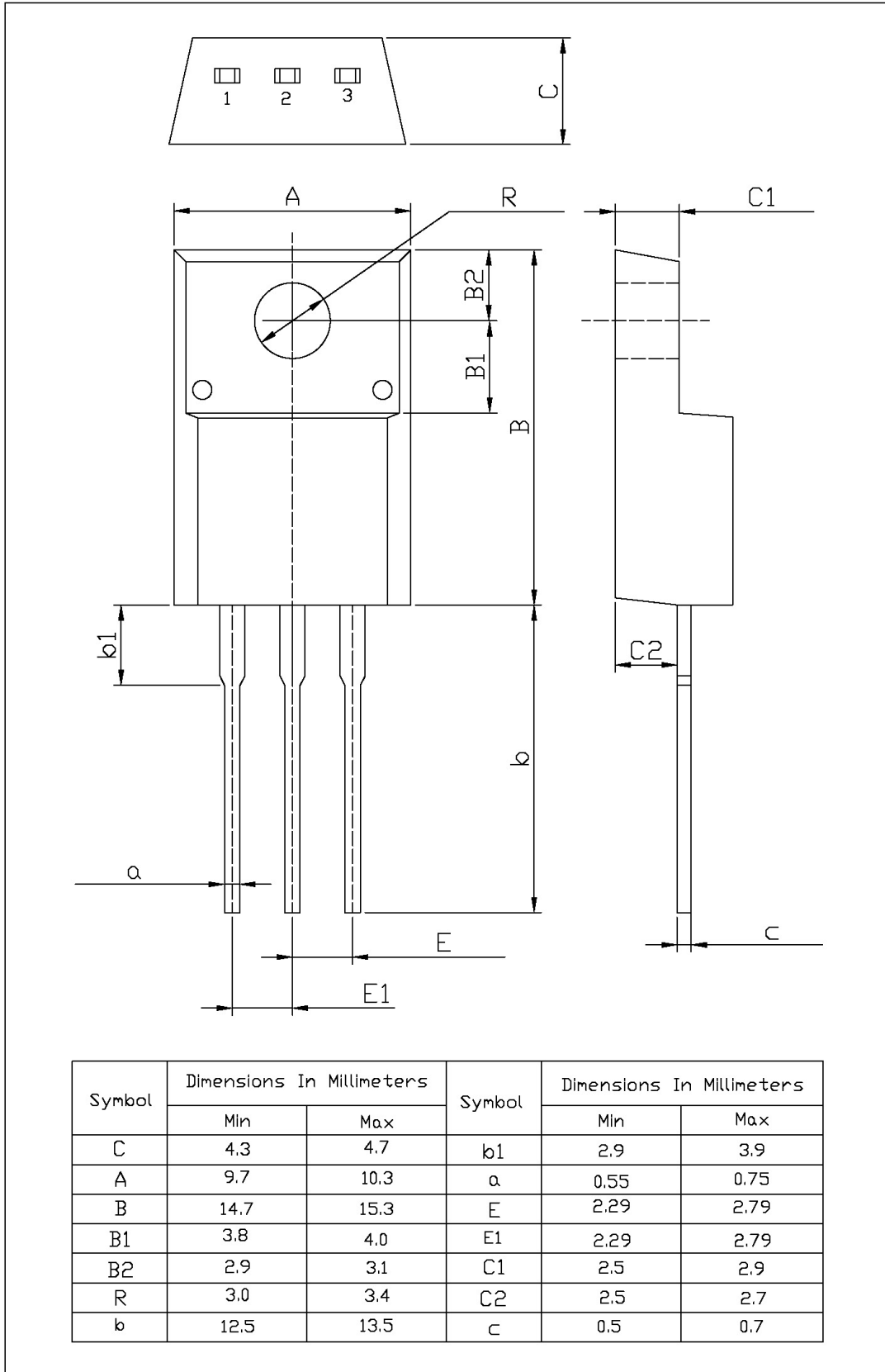


Fig24. Transient thermal resistance (MOSFET)

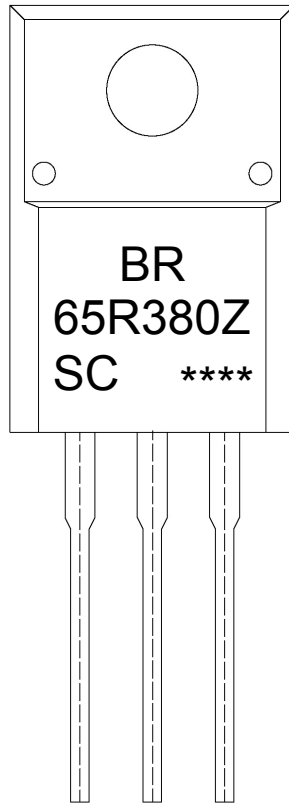
外形尺寸图 / Package Dimensions

TO-220F

单位: mm



## 印章说明 / Marking Instructions



说明：

BR： 为公司代码

65R380Z： 为型号代码

SC： 为碳化硅

\*\*\*\*： 为生产批号代码，随生产批号变化

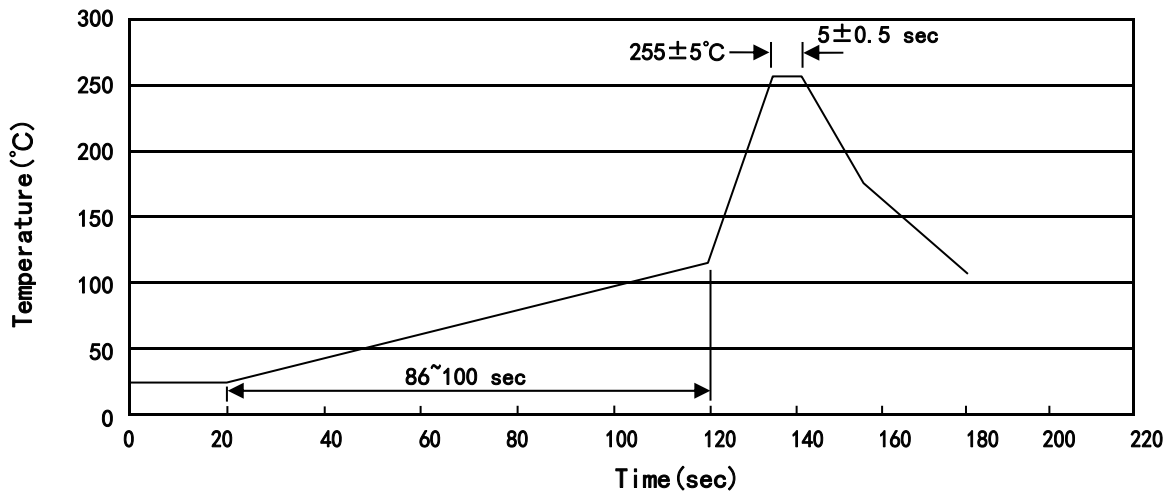
Note:

BR: Company Code

65R380Z: Product Type Code

SC: SiC

\*\*\*\*: Lot No. Code, code change with Lot No.

**波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)**


说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**直插式封装耐焊接热试验条件 / In-line Package Resistance to Soldering Heat Test Conditions**

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

**使用说明 / Notices**

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